IMPACT
International Microsystems , Packaging, Assembly and Circuits Technology conference

IMPACT-IAAC 2013 Call for Papers Now is Open

Submit Your Abstract Before June 15!

Accepted Papers Will Be Collected in IEEE Xplore!

International Microsystems, Packaging, Assembly and Circuits Technology Conference—IMPACT 2013 call for paper is open now! This year, the 2nd IAAC (IMAPS All Asia Conference) is rotated in Taiwan and joined with IMPACT 2013. To cater for the technology trends, the theme of IMPACT-IAAC 2013 highlights **"Green & Cloud: Creating Value and Toward Eco-life"**. In addition, the IMPACT Best Student Paper Award winner will be invited to join ECWC 13 in Nürnberg, Germany next year. Do you have any new discovery or stunning research? Summit your paper to IMPACT-IAAC 2013 conference before June 15th immediately. It is truly your best access and practice to this new paradigm shift.

IMPACT-IAAC 2013 which is jointly organized by IEEE CPMT-Taipei, iMAPS-Taiwan, ITRI and TPCA, and co-organized by ISU, NTU, SMTA and TTMA , and keeps collaborating with International organizations such as ICEP from Japan and iNEMI from U.S.A.. As usual, IMPACT-IAAC 2013 will be held in conjunction with TPCA Show on Oct. 22-25, 2013, at Taipei Nangang Exhibition Hall. To construct a complete spectrum of technology trends, the theme of IMPACT-IAAC 2013 highlights **"Green & Cloud: Creating Value and Toward Eco-life"**. Over the past years, IMPACT conference continually pay attention to the latest trends of global micro-system, packaging and circuit technology, and encourage the development and research of new materials, processes and designs in realizing the versatile system demands for advanced consumer, communication, cloud & mobile computing, medical and automobile applications. In order to avoid dangerous climate change, provide sustainable green energy and better life for global population, the ICT products and services need to gain further effective improvements in system performance and integration, and innovate to reduce environmental impact.

IMPACT-IAAC 2013 will arrange Panel Sessions, invited talks, industrial sessions and outstanding paper presentations. The series of IMPACT conferences has been acknowledged as successful annual gathering to share high quality papers and facilitate international participation. Furthermore, this year, TPCA offers the IMPACT Best Student Paper Award winner traveling to Germany to join ECWC 13 conference in 2014. Want to win the ticket to Nürnberg? Researchers in academia, industries and research institutes, submit your paper before June 15. Your participation is a key to cross-domain communication and inter-field innovation, and this Conference is believed to become an important and valuable resource under your contribution and participation.

Conference: IMPACT-IAAC 2013

Exhibition: TPCA Show 2013

Theme: **Green & Cloud: Creating Value and Toward Eco-life**

Date: Oct 22 (Tue.)-25(Fri.), 2013

Venue: Taipei Nangang Exhibition Hall

On-line Submission：**http://www.impact.org.tw**

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SCOPE OF PAPER SOLICITED

Packaging	PCB
P1 -Advanced Packaging Technologies	B1. Green Materials and Process
P2. Green Packaging	B2. Test, Quality, Inspection and Reliability Technology
P3-3D Integration	B3. HDI and Embedded Technology
P4-LED & Optoelectronics Packaging	B4. Electro Deposition and Electrochemical Processing Technology
P5-Interconnections & Nanotechnology	B5. Advanced and Emerging Technology
P6-Modeling, Simulation & Design	B6. Mechatronics and Automation
P7-Thermal Management	B7. Marketing & Management
P8- Advanced Sensor & Microsystems Technology (MST)	
P9-Advanced Materials, Automatic Process & Assembly	
P10-Emerging Systems Packaging Technologies	

*** Papers relevant with the above scopes are encouraged to submit but NOT limited to.**

*** Conference authority keeps the right to final session arrangement.**

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline	**June 15, 2013**	**400-500 words Submit on-line through conference website**
Abstract Acceptance Notification	July 10, 2013	Notice sent via email
Advanced Program & Pre-registration Announcement	August 15, 2013	Final session arrangement and announce advanced program
Full Paper Submission (PDF)	August 15, 2013	4 pages including figures and tables Submit on-line through conference website
Presentation Material Submission (Oral Presentation)	October 1, 2013	15 minutes presentation with 5 minutes Q&A. Please email it to the secretariat

PAPER AWARD

Best Student Paper Award and Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored at the conference.

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